SGM2045S
300mA, Low V_{IN}, Ultra-Low Noise and High PSRR Linear Regulator

GENERAL DESCRIPTION

The SGM2045S is an ultra-low noise, low V_{IN}, high PSRR, high accuracy and low dropout voltage linear regulator. It is capable of supplying 300mA output current with typical dropout voltage of only 100mV. The operating input voltage range is from 1.2V to 5.5V and output voltage range is from 1.2V to 3.3V.

Other features include logic-controlled shutdown mode, short-circuit current limit and thermal shutdown protection. The SGM2045S has automatic discharge function to quickly discharge V_{OUT} in the disabled status.

The SGM2045S is suitable for applications which need low noise and fast transient response power supply, such as power supply of camera module in smart phone, etc.

The SGM2045S is available in a Green XTDFN-1×1-4L package. It operates over an operating temperature range of -40℃ to +125℃.

FEATURES

- **Operating Input Voltage Range: 1.2V to 5.5V**
- **Fixed Outputs of 1.2V, 1.8V, 2.8V, 3.0V, 3.3V**
- **300mA Output Current**
- **Output Voltage Accuracy: ±1% at +25℃**
- **Low Quiescent Current: 15μA (TYP)**
- **Low Dropout Voltage:**
  100mV (TYP) at 300mA when V_{OUT} = 1.8V
- **Ultra-Low Noise: 9.5μV_{RMS} (TYP)**
- **High PSRR: 92dB (TYP) at 1kHz**
- **Current Limiting and Thermal Protection**
- **Excellent Load and Line Transient Responses**
- **With Output Automatic Discharge**
- **Stable with Small Case Size Ceramic Capacitors**
- **Shutdown Supply Current: 0.03μA (TYP)**
- **-40℃ to +125℃ Operating Temperature Range**
- **Available in a Green XTDFN-1×1-4L Package**

APPLICATIONS

Portable Electronic Devices
Smoke Detectors
IP Cameras
Wireless LAN Devices
Battery-Powered Equipment
Smartphones and Tablets
Digital Cameras and Audio Devices

TYPICAL APPLICATION

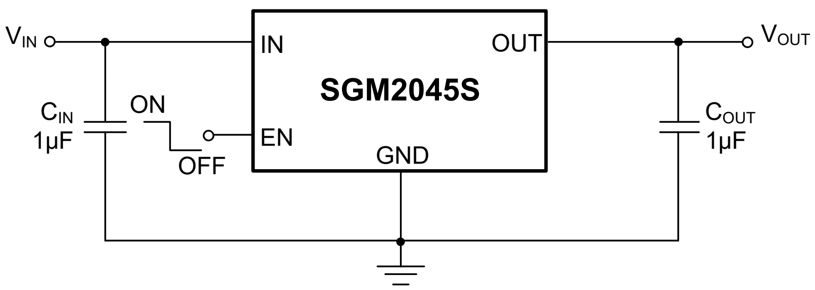


Figure 1. Typical Application Circuit

PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGM2045S-1.20	XTDFN-1×1-4L	-40℃ to +125℃	SGM2045S-1.20XXDH4G/TR	16	Tape and Reel, 10000
SGM2045S-1.80	XTDFN-1×1-4L	-40℃ to +125℃	SGM2045S-1.80XXDH4G/TR	17	Tape and Reel, 10000
SGM2045S-2.80	XTDFN-1×1-4L	-40℃ to +125℃	SGM2045S-2.80XXDH4G/TR	19	Tape and Reel, 10000
SGM2045S-3.00	XTDFN-1×1-4L	-40℃ to +125℃	SGM2045S-3.00XXDH4G/TR	20	Tape and Reel, 10000
SGM2045S-3.30	XTDFN-1×1-4L	-40℃ to +125℃	SGM2045S-3.30XXDH4G/TR	21	Tape and Reel, 10000

MARKING INFORMATION

YY

Serial Number

Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

IN to GND .... -0.3V to 6V
EN to GND... -0.3V to 6V
OUT to GND .... -0.3V to (V_{IN} + 0.3V)
Package Thermal Resistance
XTDFN-1×1-4L, $θ_{JA}$.. 242℃/W
XTDFN-1×1-4L, $θ_{JB}$.. 107℃/W
XTDFN-1×1-4L, $θ_{JC}$ .... 238℃/W
Junction Temperature...+150℃
Storage Temperature Range ....-65℃ to +150℃
Lead Temperature (Soldering, 10s)............................+260℃
ESD Susceptibility
HBM...8000V
CDM 1000V

RECOMMENDED OPERATING CONDITIONS

Input Voltage Range ....1.2V to 5.5V
Enable Input Voltage Range ....0V to 5.5V
Input Effective Capacitance, C_{IN} .... 0.1μF (MIN)
Output Effective Capacitance, C_{OUT}........... 0.5μF to 200μF (1)
Operating Junction Temperature Range......-40℃ to +125℃

NOTE:
1. To maintain a 100μA minimum output current when the output effective capacitance is more than 10μF.

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

ESD SENSITIVITY CAUTION

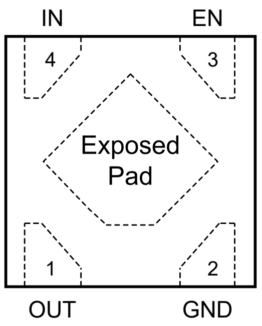
This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

PIN CONFIGURATION

(TOP VIEW)



XTDFN-1×1-4L

PIN DESCRIPTION

PIN	NAME	FUNCTION
1	OUT	Regulator Output Pin. It is recommended to use a ceramic capacitor with effective capacitance in the range of 0.5μF to 200μF to ensure stability. This ceramic capacitor should be placed as close as possible to OUT pin.
2	GND	Ground.
3	EN	Enable Pin. Drive EN high to turn on the regulator. Drive EN low to turn off the regulator. The EN pin has an internal 0.03μA pull-down current source which ensures that the device is turned off when the EN pin is floated. This pin must be connected to IN pin if enable functionality is not used.
4	IN	Input Supply Voltage Pin. It is recommended to use a 1μF or larger ceramic capacitor from IN pin to ground to get good power supply decoupling. This ceramic capacitor should be placed as close as possible to IN pin.
Exposed Pad	—	Exposed Pad. Connect it to a large ground plane to maximize thermal performance; this pad is not an electrical connection point.

ELECTRICAL CHARACTERISTICS

(V_{IN} = $V_{OUT(NOM)}$ + 0.3V, V_{EN} = V_{IN}, C_{IN} = C_{OUT} = 1μF, T_J = -40℃ to +125℃, typical values are at T_J = +25℃, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
Input Voltage Range	V_{IN}	I_{OUT} = 100mA		1.2		5.5	V
		I_{OUT} = 200mA		1.3		5.5	
		I_{OUT} = 300mA		1.4		5.5	
Output Voltage Accuracy	V_{OUT}	V_{IN} = ($V_{OUT(NOM)}$ + 0.3V) to 5.5V, I_{OUT} = 0.1mA, T_J = +25℃		-1		1	%
		V_{IN} = ($V_{OUT(NOM)}$ + 0.3V) to 5.5V, I_{OUT} = 0.1mA to 300mA		-2.5		2.5	
Line Regulation	ΔV_{LNR}	V_{IN} = ($V_{OUT(NOM)}$ + 0.3V) to 5.5V, I_{OUT} = 0.1mA			0.05	2.5	mV
Load Regulation	$\Delta V_{LDR}/V_{OUT}$	I_{OUT} = 0.1mA to 300mA			0.4	10	mV/V
Dropout Voltage [1]	V_{DROP}	I_{OUT} = 100mA	1.2V ≤ $V_{OUT(NOM)}$ < 1.5V		65	110	mV
		I_{OUT} = 200mA	1.2V ≤ $V_{OUT(NOM)}$ < 1.5V		125	210	
		I_{OUT} = 300mA	1.2V ≤ $V_{OUT(NOM)}$ < 1.5V		185	300	
			1.5V ≤ $V_{OUT(NOM)}$ < 1.8V		125	220	
			1.8V ≤ $V_{OUT(NOM)}$ < 2.8V		100	190	
			2.8V ≤ $V_{OUT(NOM)}$ ≤ 3.3V		70	150	
Output Current Limit	I_{LIMIT}	V_{OUT} = 90% × $V_{OUT(NOM)}$, V_{IN} = $V_{OUT(NOM)}$ + 0.3V	T_J = -20℃ to +125℃	300	600		mA
			T_J = -40℃ to +125℃	260	600		
Short-Circuit Current	I_{SHORT}	V_{OUT} = 0V			380		mA
Quiescent Current	I_Q	I_{OUT} = 0mA			15	40	μA
Shutdown Supply Current	I_{SHDN}	V_{EN} = 0V, V_{IN} = 5.5V			0.03	2	μA
EN Input Threshold Voltage	V_{IH}	V_{IN} = 1.2V to 5.5V		0.7			V
	V_{IL}					0.3	
EN Pull-Down Current	I_{EN}	V_{EN} = 5.5V, V_{IN} = 5.5V			0.03	1	μA
Output Discharge Resistance	R_{DIS}	V_{EN} = 0V, V_{OUT} = 0.2V, V_{IN} = 3.3V			60		Ω
Turn-On Time	t_{ON}	From EN rising from 0V to V_{IN} to 90% × $V_{OUT(NOM)}$, no load			100	240	μs
Power Supply Rejection Ratio	PSRR	I_{OUT} = 20mA, $V_{OUT(NOM)}$ = 1.8V, V_{IN} = 2.8V	f = 100Hz		90		dB
			f = 1kHz		92		
			f = 10kHz		80		
			f = 100kHz		53		
Output Voltage Noise	e_n	f = 10Hz to 100kHz, I_{OUT} = 20mA, $V_{OUT(NOM)}$ = 1.8V			9.5		μV_{RMS}
Thermal Shutdown Temperature	T_{SHDN}				160		℃
Thermal Shutdown Hysteresis	ΔT_{SHDN}				20		℃

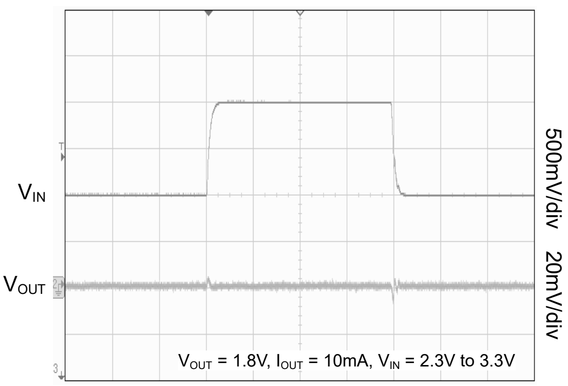
NOTE:

1. The dropout voltage is defined as the difference between V_{IN} and V_{OUT} when V_{OUT} falls to ($V_{OUT(NOM)}$ - 50mV).

TYPICAL PERFORMANCE CHARACTERISTICS

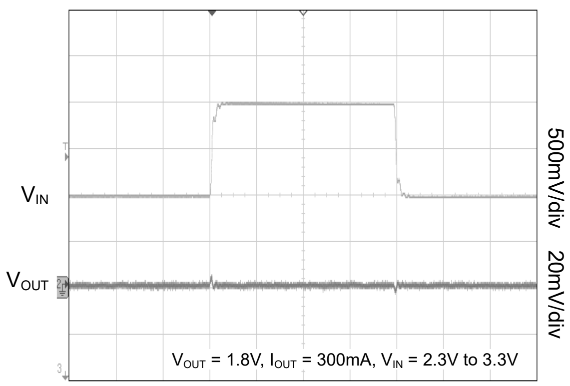
T_J = +25℃, V_{IN} = $V_{OUT(NOM)}$ + 0.3V, V_{EN} = V_{IN}, C_{IN} = C_{OUT} = 1µF, unless otherwise noted.

Line Transient Response



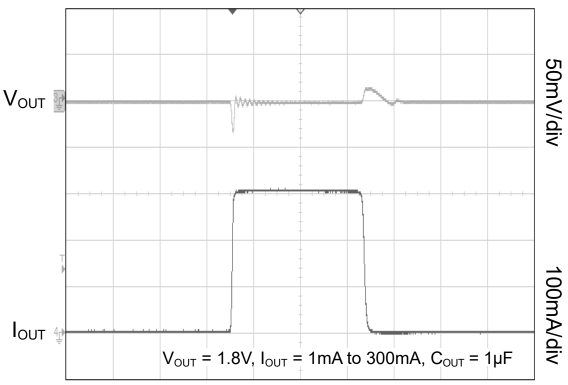
Time (20µs/div)

Line Transient Response



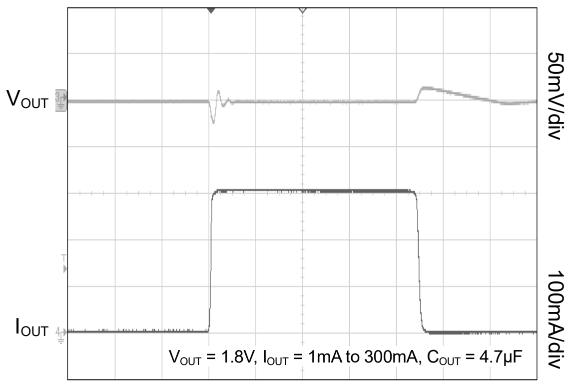
Time (20µs/div)

Load Transient Response



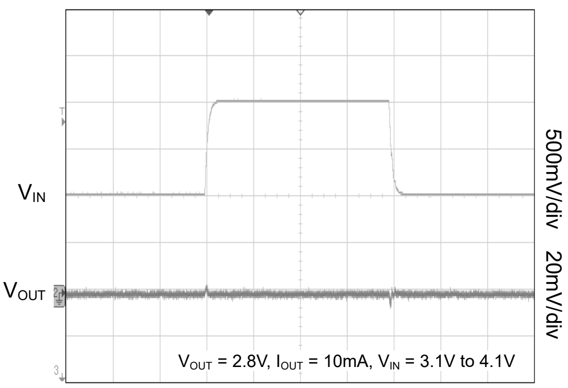
Time (10µs/div)

Load Transient Response



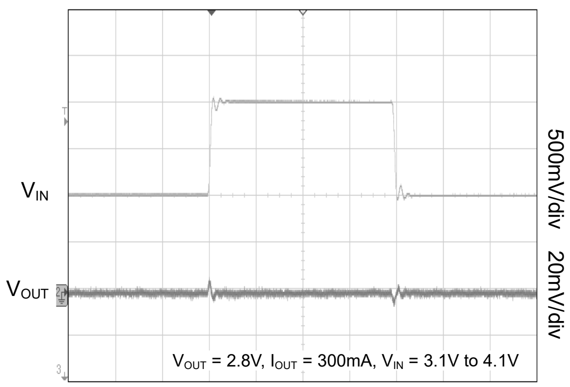
Time (10µs/div)

Line Transient Response



Time (20µs/div)

Line Transient Response

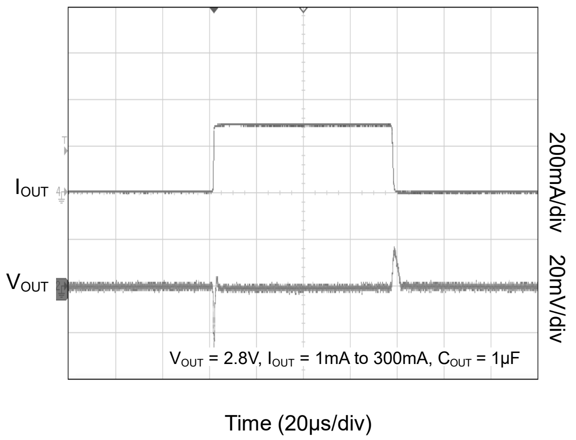


Time (20µs/div)

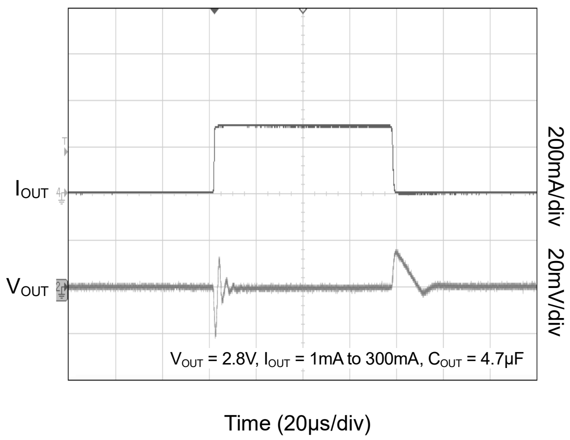
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

T_J = +25℃, V_{IN} = $V_{OUT(NOM)}$ + 0.3V, V_{EN} = V_{IN}, C_{IN} = C_{OUT} = 1μF, unless otherwise noted.

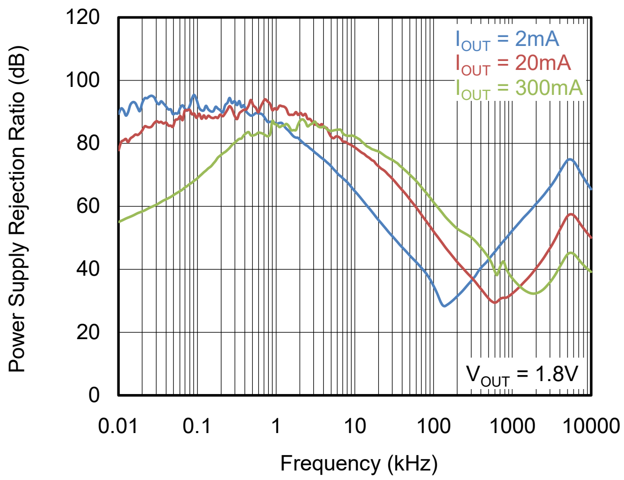
Load Transient Response



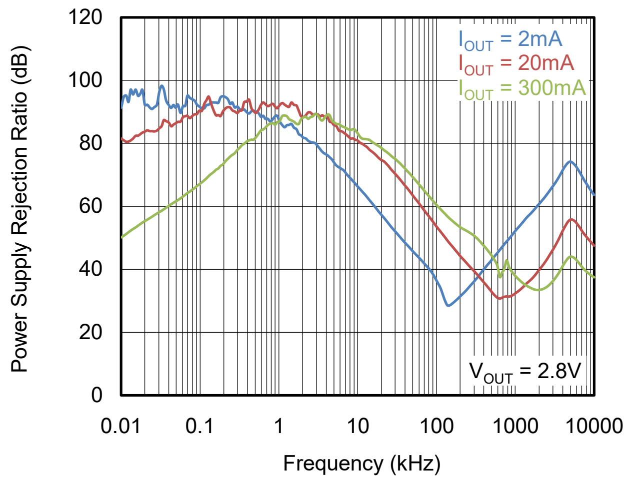
Load Transient Response



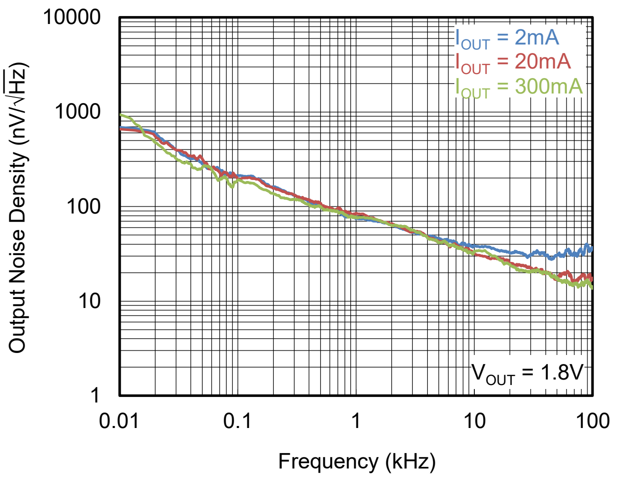
Power Supply Rejection Ratio vs. Frequency



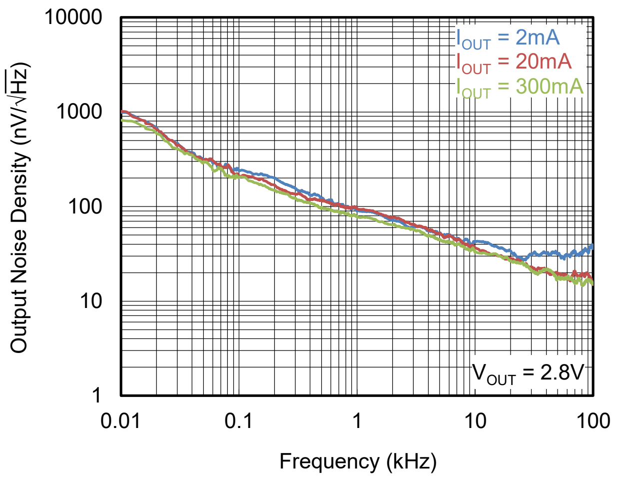
Power Supply Rejection Ratio vs. Frequency



Output Noise Density vs. Frequency



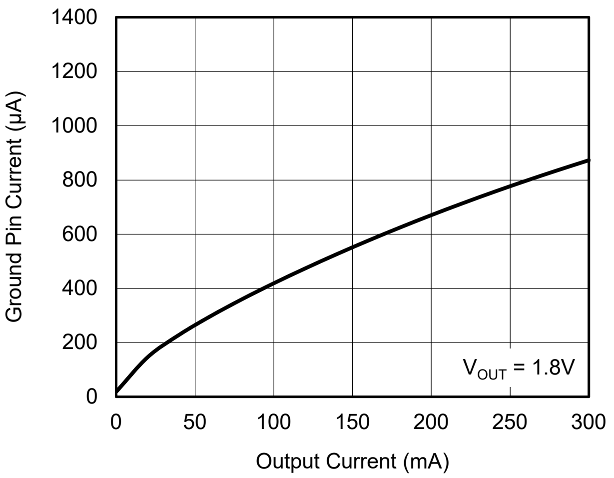
Output Noise Density vs. Frequency



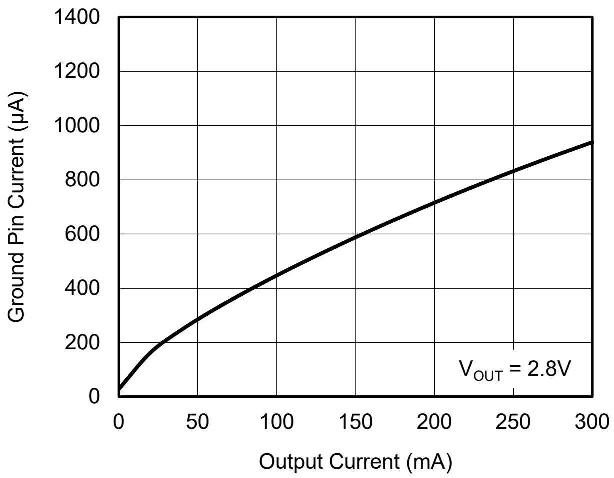
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

T_J = +25℃, V_{IN} = $V_{OUT(NOM)}$ + 0.3V, V_{EN} = V_{IN}, C_{IN} = C_{OUT} = 1μF, unless otherwise noted.

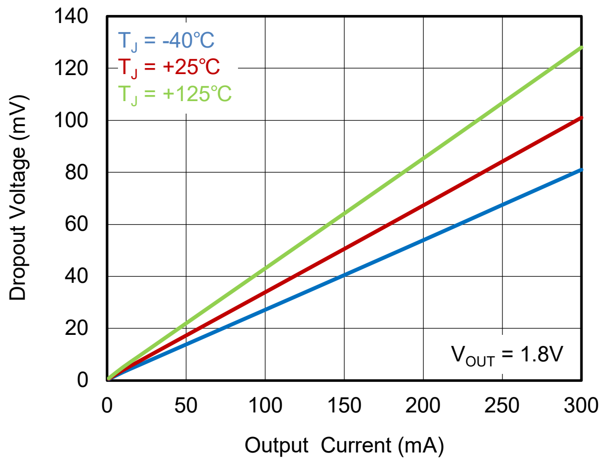
Ground Pin Current vs. Output Current



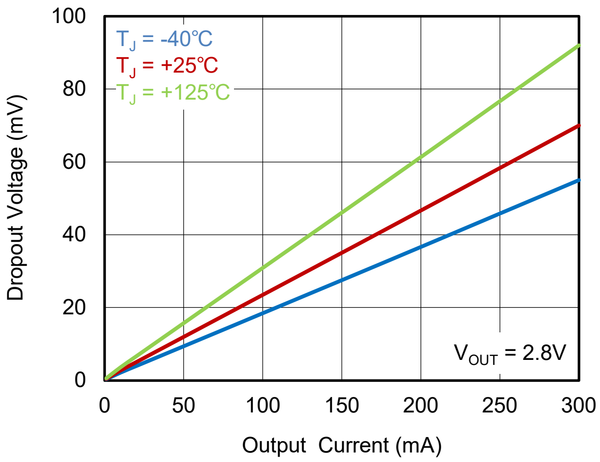
Ground Pin Current vs. Output Current



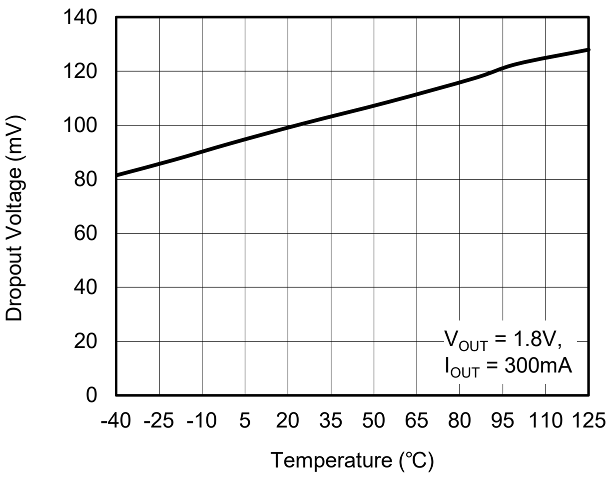
Dropout Voltage vs. Output Current



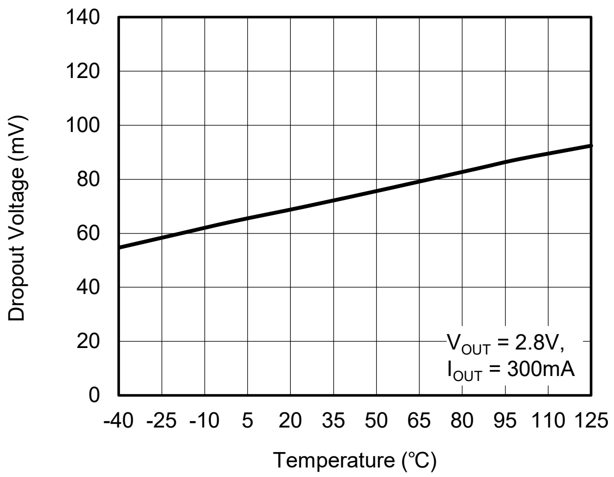
Dropout Voltage vs. Output Current



Dropout Voltage vs. Temperature

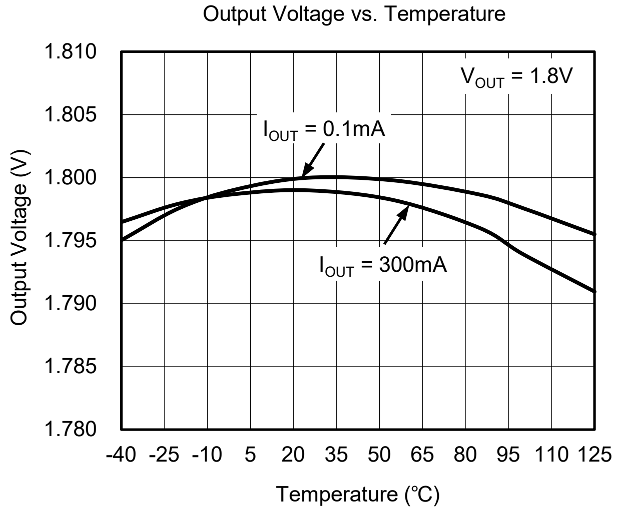


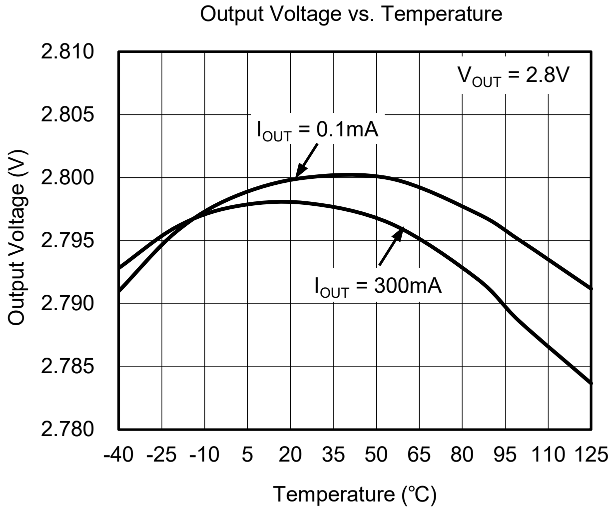
Dropout Voltage vs. Temperature

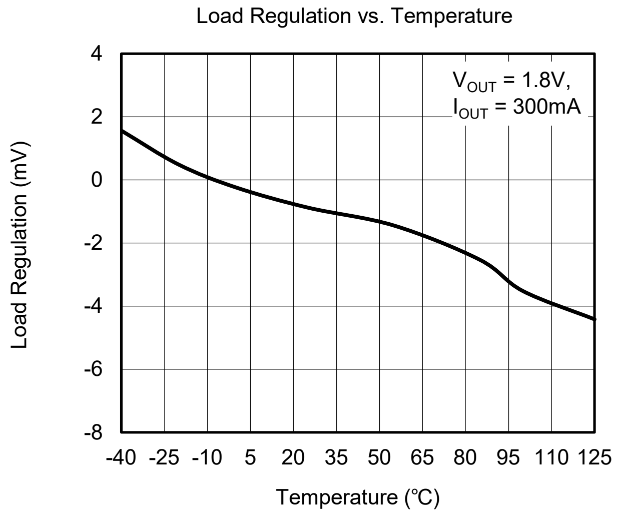


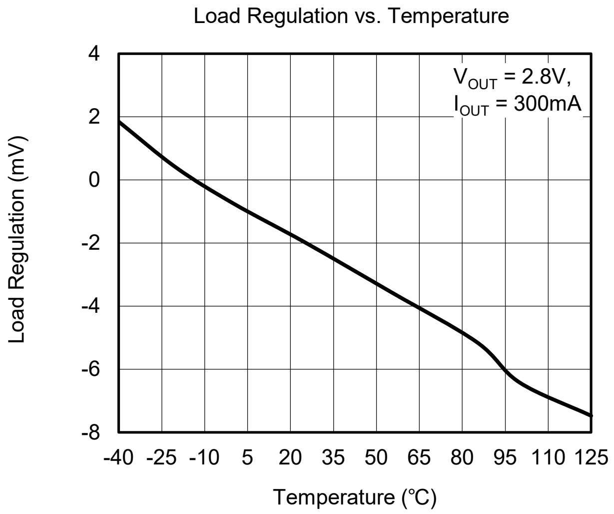
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

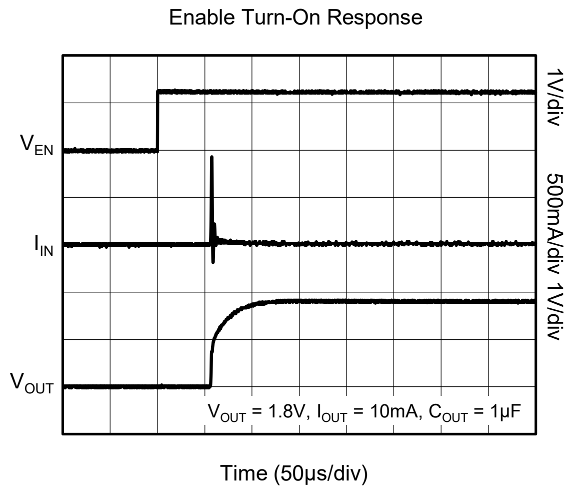
T_J = +25℃, V_{IN} = $V_{OUT(NOM)}$ + 0.3V, V_{EN} = V_{IN}, C_{IN} = C_{OUT} = 1μF, unless otherwise noted.

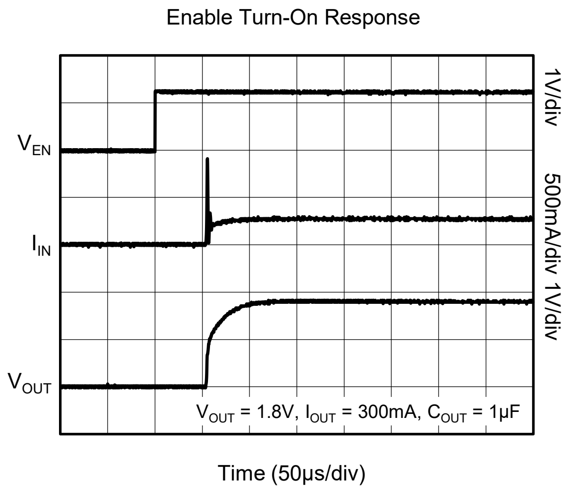








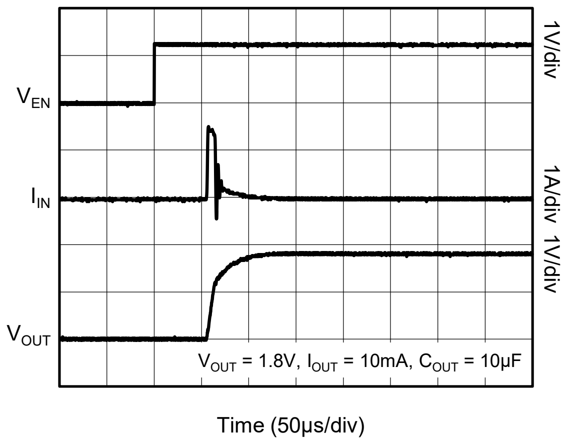




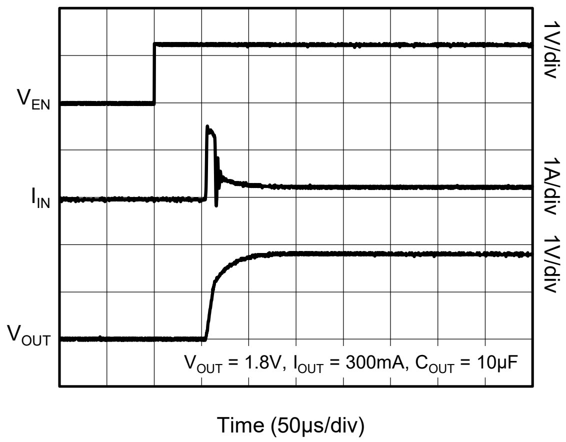
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

T_J = +25℃, V_{IN} = $V_{OUT(NOM)}$ + 0.3V, V_{EN} = V_{IN}, C_{IN} = C_{OUT} = 1μF, unless otherwise noted.

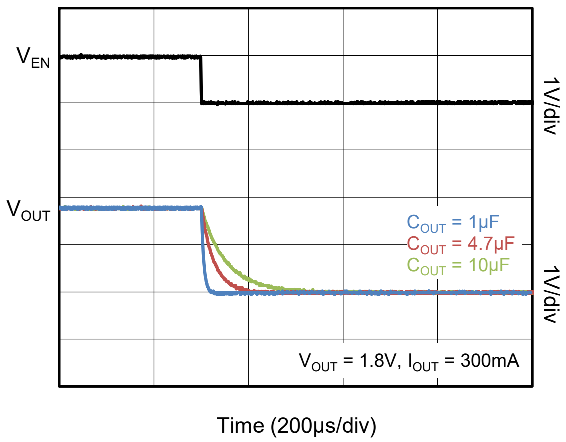
Enable Turn-On Response



Enable Turn-On Response



Enable Turn-Off Response



FUNCTIONAL BLOCK DIAGRAM

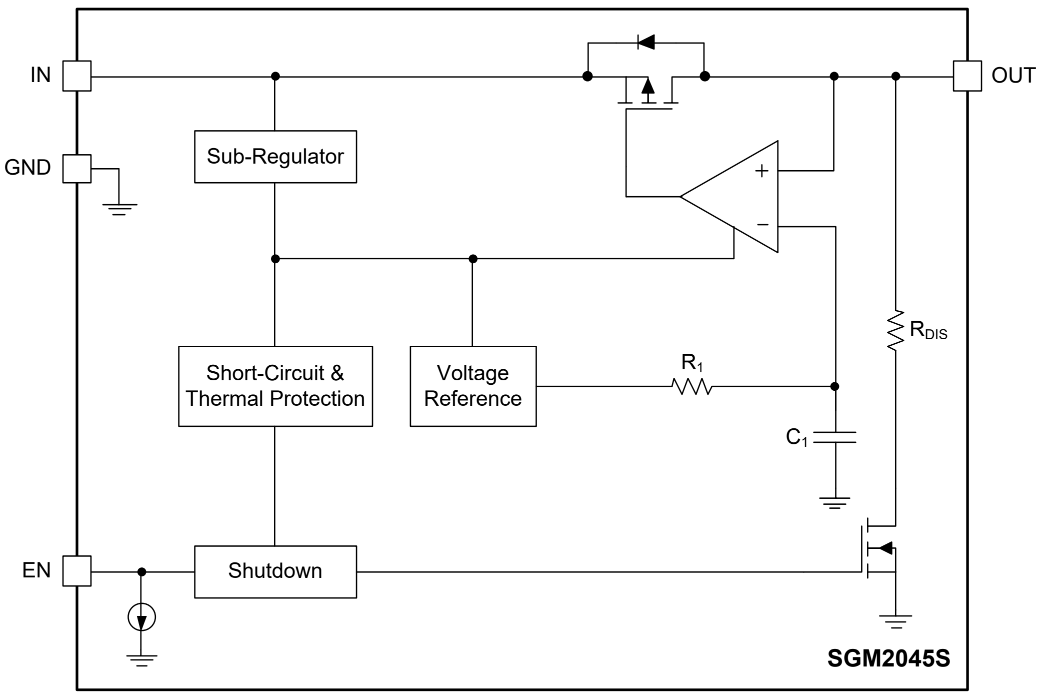


Figure 2. Block Diagram

APPLICATION INFORMATION

The SGM2045S is a low V_{IN}, ultra-low noise and low dropout LDO and provides 300mA output current. These features make the device a reliable solution to solve many challenging problems in the generation of clean and accurate power supply. The high performance also makes the SGM2045S useful in a variety of applications. The SGM2045S provides the protection functions for output overload, output short-circuit condition and overheating.

The SGM2045S provides an EN pin as an external chip enable control to enable/disable the device. When the regulator is in shutdown state, the shutdown current consumes as low as 0.03μA (TYP).

Input Capacitor Selection (C_{IN})

The input decoupling capacitor should be placed as close as possible to the IN pin for ensuring the device stability. 1μF or larger X7R or X5R ceramic capacitor is selected to get good dynamic performance.

When V_{IN} is required to provide large current instantaneously, a large effective input capacitor is required. Multiple input capacitors can limit the input tracking inductance. Adding more input capacitors is available to restrict the ringing and to keep it below the device absolute maximum ratings.

Output Capacitor Selection (C_{OUT})

The output capacitor should be placed as close as possible to the OUT pin. 1μF or larger X7R or X5R ceramic capacitor is selected to get good dynamic performance. The minimum effective capacitance of C_{OUT} that SGM2045S can remain stable is 0.5μF. For ceramic capacitor, temperature, DC bias and package size will change the effective capacitance, so enough margin of C_{OUT} must be considered in design. Additionally, C_{OUT} with larger capacitance and lower ESR will help increase the high frequency PSRR and improve the load transient response.

Enable Operation

The EN pin of the SGM2045S is used to enable/ disable its device and to deactivate/activate the output automatic discharge function.

When the EN pin voltage is lower than 0.3V, the device is in shutdown state, there is no current flowing from IN to OUT pins. In this state, the automatic discharge transistor is active to discharge the output voltage through a 60Ω (TYP) resistor.

When the EN pin voltage is higher than 0.7V, the device is in active state, the output voltage is regulated to expected value and the automatic discharge transistor is turned off.

The EN pin is pulled down by internal 0.03μA (TYP) current source when the EN pin is floated. This current source will ensure the SGM2045S in shutdown state and reduce the power dissipation in system.

Reverse Current Protection

The PMOS power transistor has an inherent body diode. This body diode will be forward biased when $V_{OUT} > V_{IN}$. When $V_{OUT} > V_{IN}$, the reverse current flowing from the OUT pin to the IN pin will damage the SGM2045S. If $V_{OUT} > V_{IN}$ event would happen in system, one external diode will be added between OUT pin and IN pin in circuit design to protect the SGM2045S.

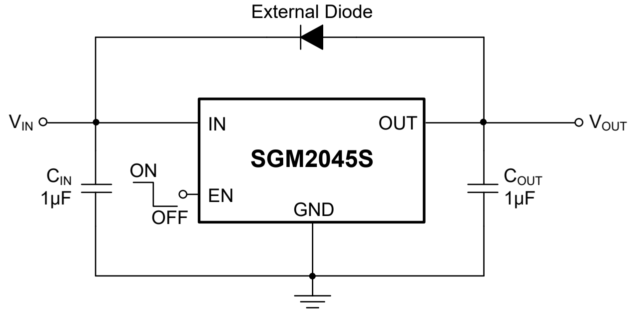


Figure 3. Reverse Protection Reference Design

Negatively Biased Output

When the output voltage is negative, the chip may not start up due to parasitic effects. Ensure that the output is greater than -0.3V under all conditions. If negatively biased output is excessive and expected in the application, a Schottky diode can be added between the OUT pin and GND pin.

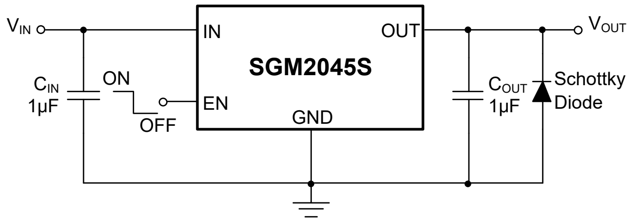


Figure 4. Negatively Biased Output Application

APPLICATION INFORMATION (continued)

Output Current Limit and Short-Circuit Protection

When overload events happen, the output current is internally limited to 600mA (TYP). When the OUT pin is shorted to ground, the short-circuit protection will limit the output current to 380mA (TYP).

Thermal Shutdown

The SGM2045S can detect the temperature of die. When the die temperature exceeds the threshold value of thermal shutdown, the SGM2045S will be in shutdown state and it will remain in this state until the die temperature decreases to +140℃.

Power Dissipation (P_D)

Thermal protection limits power dissipation in the SGM2045S. When power dissipation on pass element ($P_D = (V_{IN} - V_{OUT}) \times I_{OUT}$) is too much and the operating junction temperature exceeds +160℃, the OTP circuit starts the thermal shutdown function and turns the pass element off.

Therefore, thermal analysis for the chosen application is important to guarantee reliable performance over all conditions. To guarantee reliable operation, the junction temperature of the SGM2045S must not exceed +125℃.

The maximum allowable power dissipation depends on the thermal resistance of the IC package, the PCB layout, the rate of surrounding airflow, and the difference between the junction temperature and ambient temperature. The maximum power dissipation can be approximated using the following equation:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A)/\theta_{JA} \quad (1)$$

where $T_{J(MAX)}$ is the maximum junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction-to-ambient thermal resistance.

REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

AUGUST 2022 – REV.A.2 to REV.A.3	Page
Updated Recommended Operating Conditions section	2

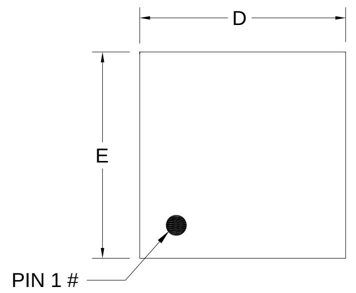
DECEMBER 2021 – REV.A.1 to REV.A.2	Page
Updated Electrical Characteristics section	4
Updated Typical Performance Characteristics section	7

OCTOBER 2021 – REV.A to REV.A.1	Page
Updated Electrical Characteristics section	4

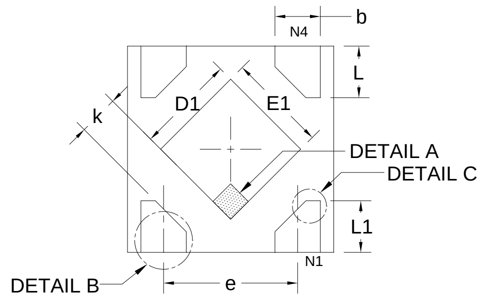
Changes from Original (SEPTEMBER 2021) to REV.A	Page
Changed from product preview to production data	All

PACKAGE OUTLINE DIMENSIONS

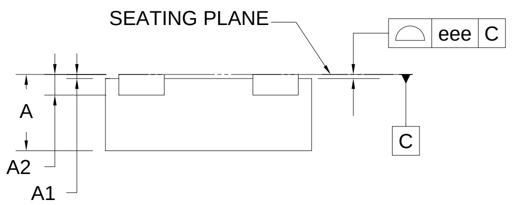
XTDFN-1×1-4L



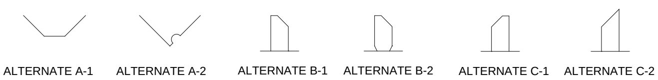
TOP VIEW



BOTTOM VIEW



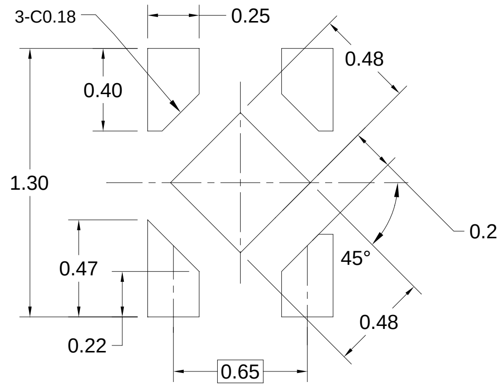
SIDE VIEW



DETAIL A ALTERNATE PIN 1 CONSTRUCTION

DETAIL B ALTERNATE TERMINAL CONSTRUCTION

DETAIL C ALTERNATE TERMINAL CONSTRUCTION



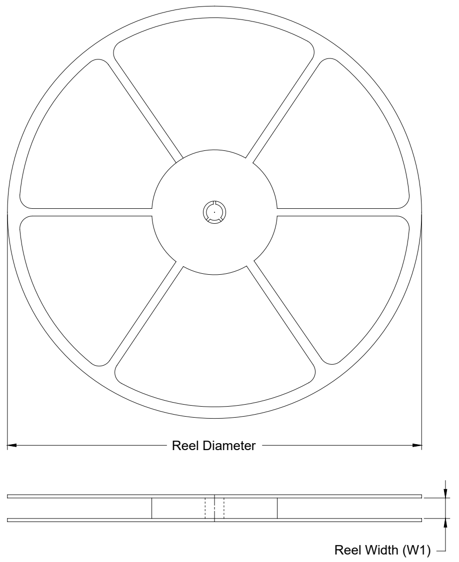
RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		
	MIN	MOD	MAX
A	0.340	0.370	0.400
A1	0.000	0.020	0.050
A2	0.100 REF		
b	0.170	-	0.300
D	0.950	1.000	1.050
E	0.950	1.000	1.050
D1	0.430	0.480	0.530
E1	0.430	0.480	0.530
L	0.200	0.250	0.300
L1	0.200	-	0.370
e	0.650 BSC		
k	0.150	-	-
eee	-	0.050	-

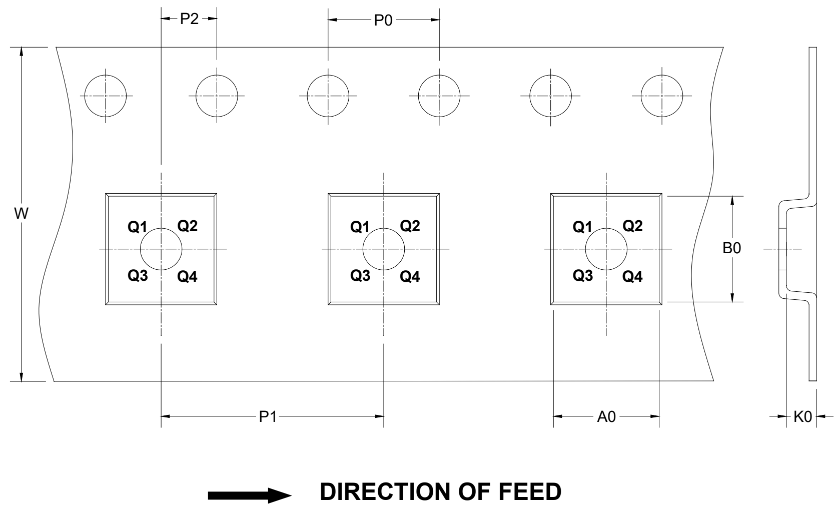
NOTE: This drawing is subject to change without notice.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



DIRECTION OF FEED

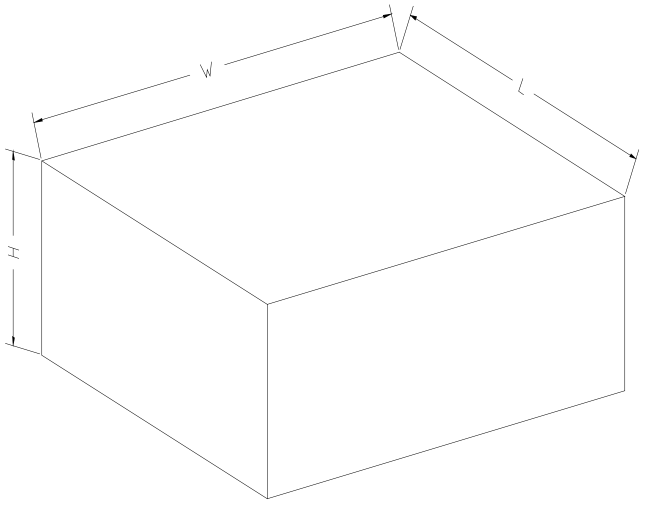
NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
XTDFN-1×1-4L	7″	9.5	1.16	1.16	0.50	4.0	2.0	2.0	8.0	Q1

DD0001

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
7″ (Option)	368	227	224	8
7″	442	410	224	18

DD0002